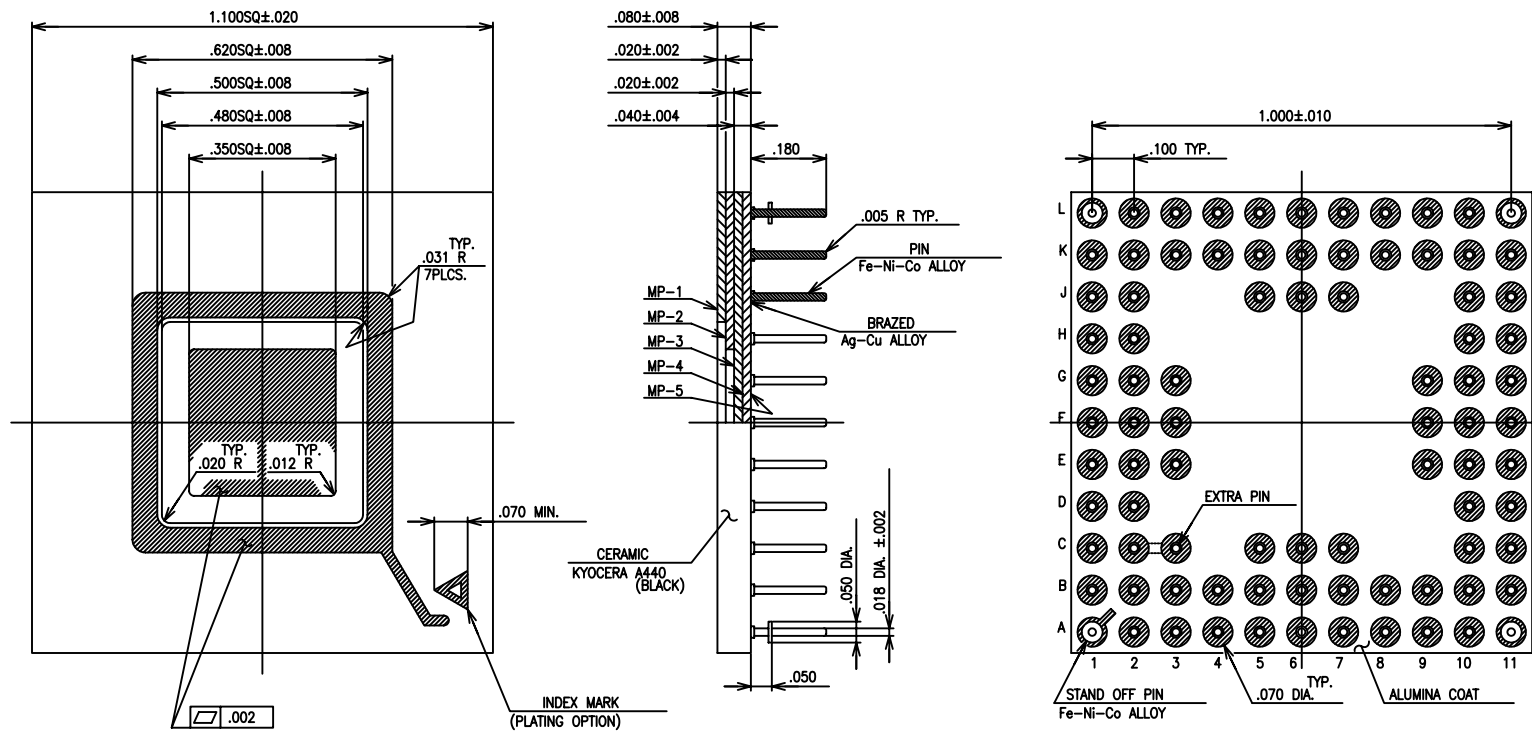


# SSM P/N CPG08405



**NOTES :**

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE :  
 B/F NO.1,11,22,32,43,53,64,74 ---300mOHM MAX.  
 THE OTHERS -----600mOHM MAX.

MODIFICATION						NAME	85 PIN GRID ARRAY PACKAGE	TOLERANCE	DRAWN   CHECKED   APPROVED   DATE					
						SCALE	5 / 1	MATERIAL	S.N   S.A   T.A   AUG.30.86					
							AS INDICATED	±.005						
						DATE	03/27/86	S.N	S.A	T.A		DRAWING NO.	KD-P86547-A	SHEET
	△ CHANGED:INDEX MARK					DATE	DRAWN	CHECKED	APPROVED					
	CHANGED													





# SSM P/N CPG08405

## WIRE BOND PAD/CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.
1	B2
2	C2
3	B1
4	C1
5	D2
6	D1
7	E3
8	E2
9	E1
10	F2
11	F3
12	G3
13	G1
14	G2
15	F1
16	H1
17	H2
18	J1
19	K1
20	J2


W/B NO.	PIN NO.
21	L1
22	K2
23	K3
24	L2
25	L3
26	K4
27	L4
28	J5
29	K5
30	L5
31	K6
32	J6
33	J7
34	L7
35	K7
36	L6
37	L8
38	K8
39	L9
40	L10

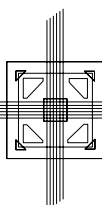
W/B NO.	PIN NO.
41	K9
42	L11
43	K10
44	J10
45	K11
46	J11
47	H10
48	H11
49	F10
50	G10
51	G11
52	G9
53	F9
54	F11
55	E11
56	E10
57	E9
58	D11
59	D10
60	C11

W/B NO.	PIN NO.
61	B11
62	C10
63	A11
64	B10
65	B9
66	A10
67	A9
68	B8
69	A8
70	B6
71	B7
72	A7
73	C7
74	C6
75	A6
76	A5
77	B5
78	C5
79	A4
80	B4

W/B NO.	PIN NO.
81	A3
82	A2
83	B3
84	A1

(EXTRA PIN)	
C3	C2
S/R	NC
D/A	NC

MODIFICATION						NAME	85 PIN GRID ARRAY PACKAGE	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						SCALE	X	UNLESS OTHERWISE SPECIFIED	S.N	S.A	T.A	AUG.30.'86
						MATERIAL		THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-P86547-A		SHEET	3/3



**SPECTRUM**  
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